

ON Semiconductor®

FDC6561AN

Dual N-Channel Logic Level PowerTrench™ MOSFET

General Description

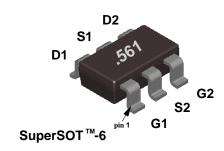
These N-Channel Logic Level MOSFETs are produced using ON Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

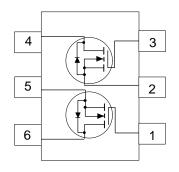
These devices are well suited for all applications where small size is desireable but especially low cost DC/DC conversion in battery powered systems.

Features

- Very fast switching.
- Low gate charge (2.1nC typical).
- SuperSOT[™]-6 package: small footprint (72% smaller than standard SO-8); low profile (1mm thick).







Absolute Maximum Ratings		e waximum Ratings	$I_A = 25$ °C unless otherwise note					

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		30	V
V_{GSS}	Gate-Source Voltage - Continuous		±20	V
I _D	Drain Current - Continuous		2.5	А
	- Pulsed		10	
P _D	Maximum Power Dissipation	(Note 1a)	0.96	W
		(Note 1b)	0.9	
		(Note 1c)	0.7	
T_J , T_{STG}	Operating and Storage Temperature Range		-55 to 150	℃
THERMA	L CHARACTERISTICS			
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)		130	°C/W
$R_{\theta JC}$	R _{AIC} Thermal Resistance, Junction-to-Case (Note 1)		60	°C/W

Symbol	Parameter	Conditions		Min	Тур	Max	Units
OFF CHARA	ACTERISTICS	•		•	•	•	•
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		30			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient	I _D = 250 μA, Referenced to	to 25 °C		23.6		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V}, \ V_{GS} = 0 \text{ V}$				1	μA
			T _J = 55 °C			10	μA
GSSF	Gate - Body Leakage, Forward	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
GSSR	Gate - Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
ON CHARA	CTERISTICS (Note 2)	<u>.</u>		•	•	•	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		1	1.8	3	V
$\Delta V_{GS(th)}/\Delta T_{J}$	Gate Threshold VoltageTemp.Coefficient	$I_D = 250 \mu\text{A}$, Referenced to	to 25 °C		-4		mV/°C
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_{D} = 2.5 \text{ A}$			0.082	0.095	Ω
(,			T _J = 125 °C		0.122	0.152	
		$V_{GS} = 4.5 \text{ V}, I_D = 2.0 \text{ A}$			0.113	0.145	Ì
I _{D(on)}	On-State Drain Current	$V_{GS} = 10 \text{ V}, V_{DS} = 5 \text{ V}$		10			Α
g _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 2.5 \text{ A}$			5		S
DYNAMIC CH	HARACTERISTICS						
C _{iss}	Input Capacitance	$V_{DS} = 15 \text{ V}, \ V_{GS} = 0 \text{ V},$			220		pF
Coss	Output Capacitance	f = 1.0 MHz			50		pF
C _{rss}	Reverse Transfer Capacitance				25		pF
SWITCHING	CHARACTERISTICS (Note 2)						
t _{D(on)}	Turn - On Delay Time	$V_{DD} = 5 \text{ V}, I_{D} = 1 \text{ A},$			6	12	ns
t _r	Turn - On Rise Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$			10	18	ns
t _{D(off)}	Turn - Off Delay Time				12	22	ns
t _r	Turn - Off Fall Time				2	6	ns
Q_g	Total Gate Charge	$V_{DS} = 15 \text{ V}, I_{D} = 2.5 \text{ A}$			2.3	3.2	nC
Q_{gs}	Gate-Source Charge	$V_{GS} = 5 V$			0.7	1	nC
Q_{gd}	Gate-Drain Charge				0.9	1.3	nC
DRAIN-SOUP	RCE DIODE CHARACTERISTICS			T	1	ı	•
I _s	Continuous Source Diode Current					0.75	Α
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 0.75 \text{ A}$	(Note 2)		0.78	1.2	V

Notes:

2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.



a. 130°C/W on a 0.125 in² pad of 2oz copper.



b. 140°C/W on a 0.005 in² pad of 2oz copper.



^{1.} $R_{\phi,k}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\phi,C}$ is guaranteed by design while $\boldsymbol{R}_{\text{\tiny BCA}}$ is determined by the user's board design.

Typical Electrical Characteristics

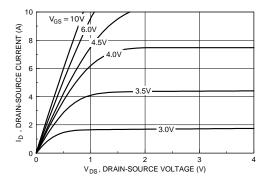


Figure 1. On-Region Characteristics.

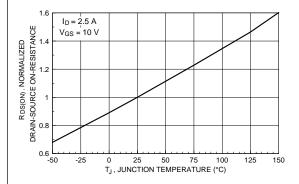


Figure 3. On-Resistance Variation with Temperature.

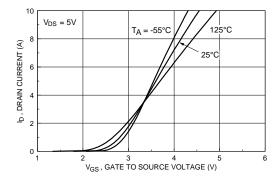


Figure 5.Transfer Characteristics.

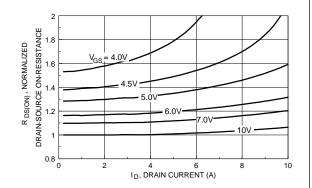


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

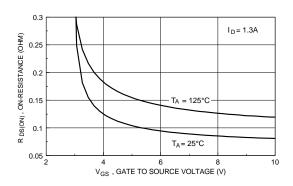


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

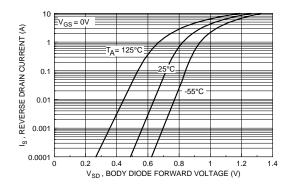


Figure 6. Body Diode Forward Voltage

Variation with Source Current
and Temperature.

Typical Electrical Characteristics (continued)

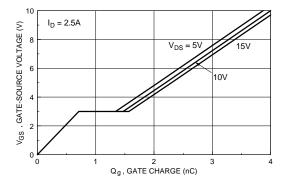


Figure 7. Gate Charge Characteristics.

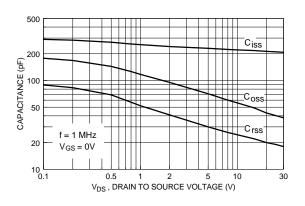


Figure 8. Capacitance Characteristics.

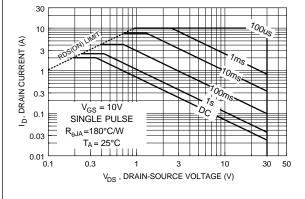


Figure 9. Maximum Safe Operating Area.

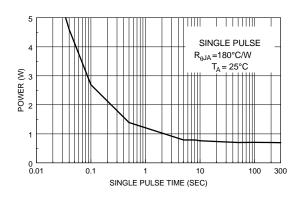


Figure 10. Single Pulse Maximum Power Dissipation.

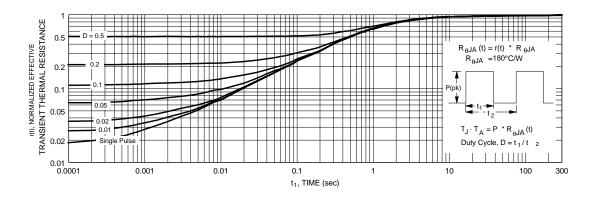


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c.

Transient thermal response will change depending on the circuit board design.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Phone: 421 33 790 2910

Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative